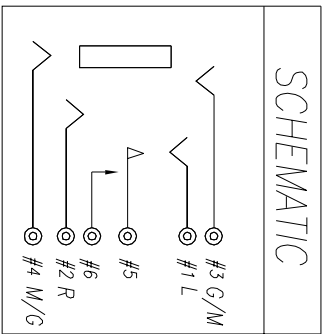
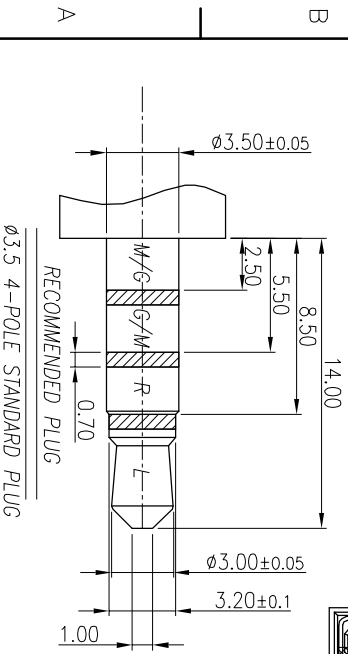


RECOMMENDED PCB LAYOUT

TOP VIEW ; TOL. ±0.05



SPECIFICATIONS:

- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
- CONTACT RESISTANCE: 50mΩ MAX.
- INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
- UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-65% IN HUMIDITY. BUT IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
- LIFE TEST: 5000 CYCLES.
- INSERTION FORCE: 0.3 - 3.0kg.
- WITHDRAWAL FORCE: 0.3 - 3.0kg.
- AFTER TEST, CONTACT RESISTANCE: 120mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK "S" ON TOP OF CONNECTOR.
- PACKING: TAPE & REEL.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: Ⓧ
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: Ⓧ

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
B	EARTH	1	COPPER ALLOY, 0.2t	ALL OVER 50" Ni.
C	RING B	1	COPPER ALLOY, 0.2t	
D	RING A	1	COPPER ALLOY, 0.2t	
E	TIP SPRING	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA WIDE S-80" ON SOLDER AREA
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA ALL OVER 50" Ni.
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60u"Min.
J	MYLAR	1	KAPTON: 7.05*4.5*0.05	YELLOW
K	MYLAR	1	KAPTON: 6.6*4.2*0.08T	BLACK

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T160114-7A	PENG	2016.11.23

DECIMALS:	ANGLES:	TITLE
X : ±0.5	X : ±2°	3.5φ PHONE JACK
X.X : ±0.3	X.X : ±1°	PART NO. 2S13095-115111F
X.XX : ±0.2		SCALE 4:1 UNIT: mm
		SIZE: A3 SHEET: 1 OF 1 REV: A
		CUSTOMER COPY

Singatron Enterprise Co., Ltd.
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